FLIP CHIP MODULES
TEST SPECS

TYPE: M302

DELAY

TEST	CONDITIONS	MAXIMUM	MINIMUM
I_{IN}	V_{CC} = +5.25 V V_{IN} = +2.4 V	+ 50 µA	
I_{IN}	V_{CC} = +5.25 V V_{IN} = +0.4 V	- 4.0 MA	
V_{OUT}	V_{CC} = +5.0 V I_L = +40 MA	+ 0.4 V	
PROPAGATION TIME	V_{CC} = +5.0 V * RC LOAD	40 NS	
DELAY TIME (T_D)	RANGE 1	≅ 900 NS	≦ 50 NS
	RANGE 2	≅ 9 µS	≦ 400 NS
	RANGE 3	≅ 90 µS	≦ 4 µS
	RANGE 4	≅ 900 µS	≦ 40 µS
	RANGE 5	≅ 9 MS	≦ 400 µS
DELAY TIME STABILITY ΔT	4.75 < V_{CC} < 5.25	5%	

* OUTPUT: RC LOAD

R = 120 Ω

C = 50 PF

11/28/67

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products. If you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting.
Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.